

2026 CHIP SEAL
REQUEST FOR BIDS

ADDENDUM #1

Project Number: IFB-COF-4-26
RFP Issued: February 27, 2026
Addendum #1 Issued: March 18, 2026
RFP Questions Deadline: March 13, 2026
Submission Deadline: March 30, 2026, at 2:30 PM (MST)

This Addendum #1 (the "Addendum 1") is hereby issued to supplement the 2026 Chip Seal Invitation for Bids (the "IFB") with answers to questions received prior to the deadline. All Offerors must acknowledge receipt of this Addendum 1, and all other and future addenda to the IFB, if any, as part of their respective Bids. This Addendum does not change the deadline to submit a Bid.

Questions and Answers:

Q: For the Chip Seal emulsion, will CRS-2P be accepted?

A: CRS-2P chip seal emulsion will be accepted.

Q: What is the dilution rate for the fog seal? (50:50) or (60:40)

A: Dilution rate for the chip seal fog will be 60:40

Q: What material are you wanting for the prime on the double 3/8"?

A: Prime material for double chip seal will be AEP or equivalent.

END OF QUESTIONS AND ANSWERS SECTION